

## Materials Declaration

<b>Package</b>	PLCC
<b>Body Size</b>	4.4
<b>LeadCount</b>	44
<b>Option</b>	PbFree

### Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy Cresol Novolac	2	3.53 E-02	14577
SiO2 Filler	86	1.52 E+00	626820
Phenol Resin	4	7.06 E-02	29155
Epoxy Resin	7.5	1.32 E-01	54665
Carbon Black	0.5	8.82 E-03	3644

### Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.9	5.70 E-01	235678
Zr	0.1	5.71 E-04	236

### Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.92 E-03	1620

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.22 E-02	9178

### Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.9	1.98 E-03	819

### Chip

	% of Chip	Weight (g)	PPM
Si	100	4.99 E-02	20626

### Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	1.80 E-03	745
Ag Filler	75	5.41 E-03	2237

### Package Totals

Weight (g)	PPM
<b>2.42 E+00</b>	<b>1000000</b>

### Molding Compound

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

### Die Attach Paste

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

Note: The information provided in this declaration are true to the best of ADI's knowledge  
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

## Materials Declaration

<b>Package</b>	PLCC
<b>Body Size</b>	4.4
<b>LeadCount</b>	44
<b>Option</b>	Sn/Pb

### Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy Cresol Novolac	16	2.78 E-01	131654
SiO2 Filler	72	1.25 E+00	592445
Phenol Novolac	8	1.39 E-01	65827
Antimony_Sb2O3	2.2	3.83 E-02	18102
Brominated Resin	1.6	2.78 E-02	13165
Carbon Black	0.2	3.48 E-03	1646

### Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

### Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.9	3.36 E-01	158825
Zr	0.1	3.36 E-04	159

### Die Attach Paste

Item	PPM	Method
Pb	<2	ICP AES
Cd	<2	ICP AES
Hg	<2	ICP AES
Cr+6	<2	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

### Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	2.63 E-03	1244

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	7.14 E-04	338
Pb	15	1.26 E-04	60

### Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.41 E-03	665

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100	2.96 E-02	13978

### Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	1.00 E-03	473
Ag Filler	75	3.00 E-03	1419

### Package Totals

Weight (g)	PPM
2.11 E+00	1000000

AMK-P-A

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ADI Proprietary

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